

Features

- High isolation 5000 VRMS
- Supports 0.3 A, 0.6 A, 0.9 A and 1.2 A
- RoHS compliant
- REACH compliance
- External creepage > 7.5mm
- Internal creepage > 6.0mm
- Insulation distance > 0.4mm
- Regulatory Approvals
 - UL UL1577 (E364000)
 - VDE EN60747-5-5(VDE0884-5)
 - CQC GB4943.1, GB8898
 - IEC60065, IEC60950

Description

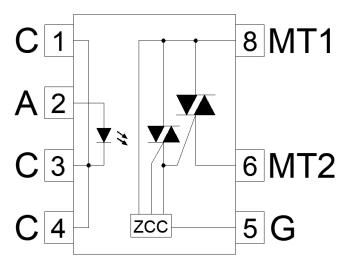
The zero crossing power Triac consists of a Triac and a photo-Triac, which is optically coupled to a gallium arsenide Infrared emitting diode, and house in a 7-lead DIP package. It also comes with different lead forming options.

Applications

- Home appliances
- Industrial equipment

Package Outline

Schematic



Note: Different bending options available. See package dimension.



Absolute Maximum Rating at 25°C

Symbol	Paramete	Ratings	Units	Notes	
Viso	Isolation voltage		5000	Vrms	
T _{OPR}	Operating temp	perature	-40 ~+85	°C	
T _{STG}	Storage tempe	erature	-40 ~+125	°C	
_	Soldering temp	perature	260	°C	
TsoL	Wave soldering te	emperature	260	°C	
Emitter			•	<u> </u>	
lF	LED forward o	current	50	mA	
V _R	LED reverse v	/oltage	6	V	
I _{FP}	Peak forward	current	1	А	
Pin	Power dissip	75	mW		
Detector			•	<u> </u>	
V _{DRM}	Repetitive peak OFF	600	V		
	Continuous Current Load	CTT0213	0.3		
I _{T(RMS)}		CTT1213	0.6	A	
		CTT2213	0.9		
		CTT3213	1.2		
		CTT0213	3		
Ітѕм	Peak Current Load	CTT1213	6	A	
		CTT2213	9		
		CTT3213	12		
Pout	Power dissipation		800	mW	
PT	Total power dissipation		850	mW	



Electrical Characteristics $T_A = 25$ °C (unless otherwise specified)

Emitter Characteristics

Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
VF	Forward voltage	I _F =10mA	-		1.3	V	
I _R	Reverse Current	V _R = 6V	-		5	μΑ	
C _{IN}	Input Capacitance	f= 1MHz	-	45	-	pF	

Detector Characteristics

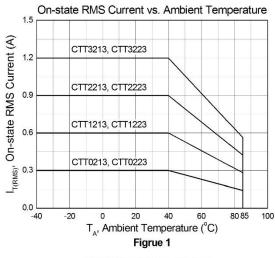
Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
I _{DRM1}	Peak Blocking Current	I _F = 0mA, V _{DRM} = 600V	-	-	100	uA	
I _{DRM2}	Inhibit Leakage Current	I _F = = Rated I _{FT} , V _{DRM} = 600V			500	uA	
V _{INH}	Inhibit Voltage	I _F = Rated I _{FT}	-	-	50	V	
V _{TM}	Peak On-State Voltage	I _F = Rated I _F T, I _{TM} = 100mA	-	-	2.5	V	
dv./dt	Critical Rate of Rise off-State	\/ Datad\/	200			\// ₁ o	
dv/dt	Voltage	V _{PEAK} = Rated V _{DRM}	200 -	-	V/µs		

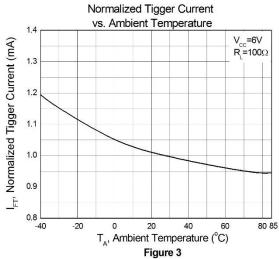
Transfer Characteristics

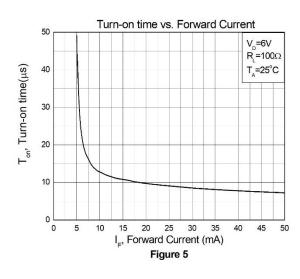
Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
I _{FT}	Input Trigger Current	Terminal Voltage = 3V	ı	ı	10	mA	
lн	Holding Current		-	-	25	mA	
Rıo	Isolation Resistance	Vio= 500VDC	1x10 ¹¹	-	-	Ω	
C _{IO}	Isolation Capacitance	f= 1MHz	-	0.25	-	pF	

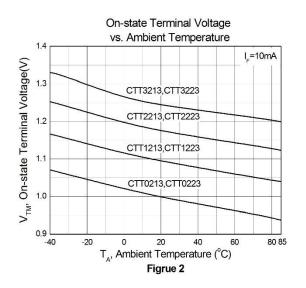


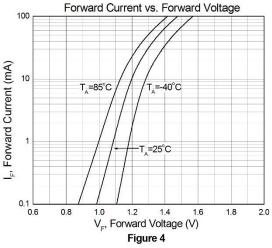
Typical Characteristic Curves

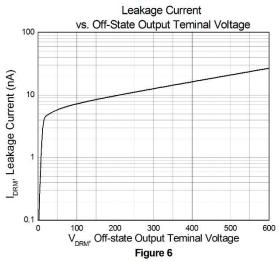




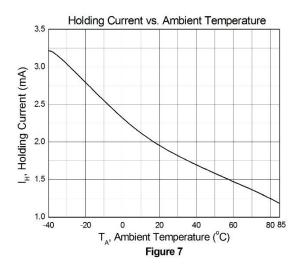


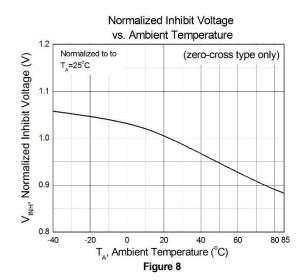








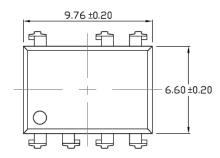


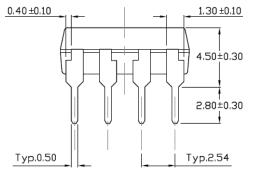


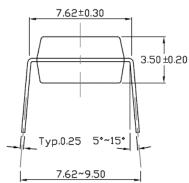


Package Dimension Dimensions in mm unless otherwise stated

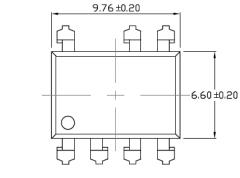
Standard DIP - Through Hole

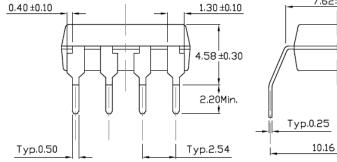






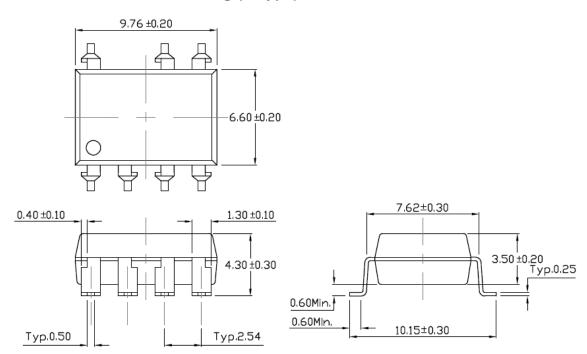
Gullwing (400mil) Lead Forming – Through Hole (M Type)



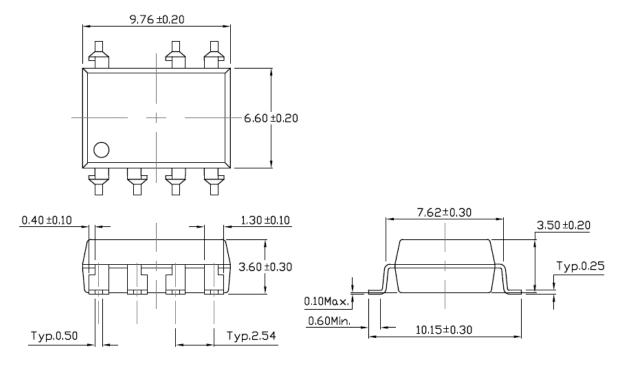




Surface Mount Lead Forming (S Type)

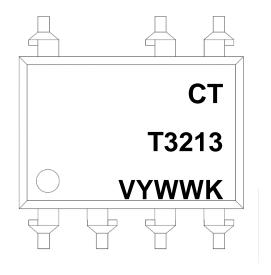


Surface Mount (Low Profile) Lead Forming (SL Type)





Device Marking



Note:

CT : Denotes "CT Micro"

T3213 : Product Number

V : VDE Safety Mark (option)

Y : Fiscal Year WW : Work Week

K : Production Code

Ordering Information

CTTX213(V)(Y)(Z)

CT = Denotes "CT Micro"

TX213 = Product Number (Current Rating Option X=0, 1, 2, or 3)

V = VDE safety mark option (V, or none)
Y = Lead form option (S, SL, M or none)
Z = Tape and reel option (T1, T2 or none)

Option	Description	Quantity
None	Standard 8 Pin Dip	40 Units/Tube
M	Gullwing (400mil) Lead Forming	40 Units/Tube
S(T1)	Surface Mount Lead Forming – With Option 1 Taping	1000 Units/Reel
S(T2)	Surface Mount Lead Forming – With Option 2 Taping	1000 Units/Reel
SL(T1)	Surface Mount (Low Profile) Lead Forming– With Option 1 Taping	1000 Units/Reel
SL(T2)	Surface Mount (Low Profile) Lead Forming- With Option 2 Taping	1000 Units/Reel

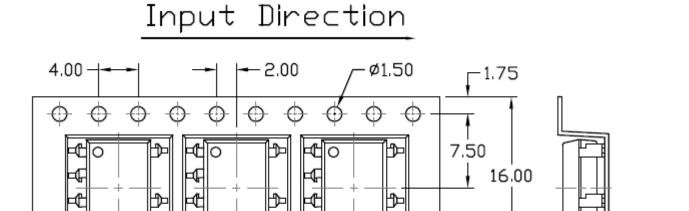


4.80

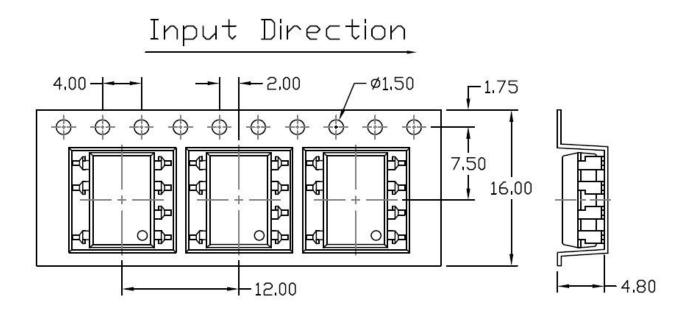
Carrier Tape Specifications Dimensions in mm unless otherwise stated

-12.00

Option S(T1) & SL(T1)



Option S(T2) & SL(T2)





Wave soldering (JEDEC22A111 compliant)

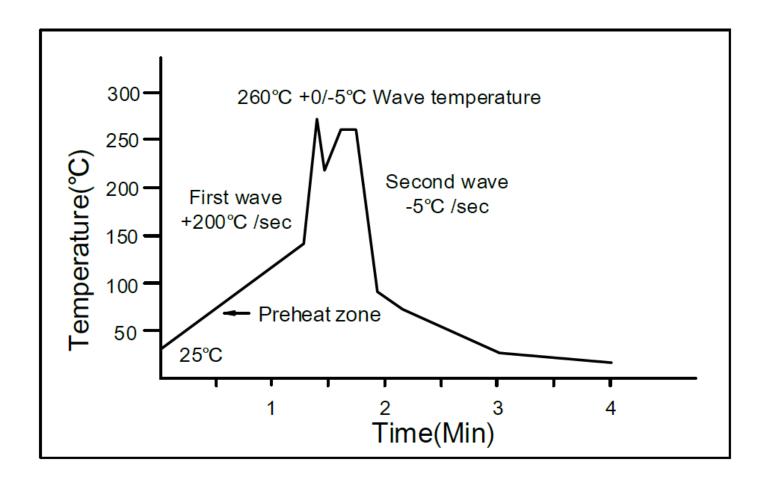
One time soldering is recommended within the condition of temperature.

Temperature: 260+0/-5°C.

Time: 10 sec.

Preheat temperature:25 to 140°C.

Preheat time: 30 to 80 sec.



Hand soldering by soldering iron

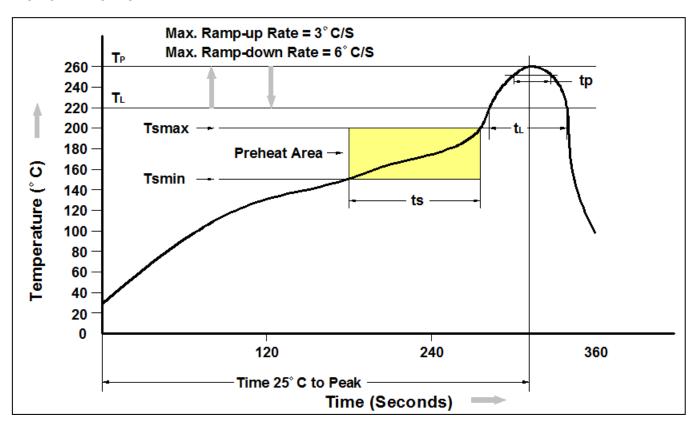
Allow single lead soldering in every single process.

One time soldering is recommended. Temperature: 350+0/-5°C

Time: 3 sec max.



Reflow Profile



Profile Feature	Pb-Free Assembly Profile
Temperature Min. (Tsmin)	150°C
Temperature Max. (Tsmax)	200°C
Time (ts) from (Tsmin to Tsmax)	60-120 seconds
Ramp-up Rate (t∟ to t₂)	3°C/second max.
Liquidous Temperature (T _L)	217°C
Time (t _L) Maintained Above (T _L)	60 – 150 seconds
Peak Body Package Temperature	260°C +0°C / -5°C
Time (t _P) within 5°C of 260°C	30 seconds
Ramp-down Rate (T _P to T _L)	6°C/second max
Time 25°C to Peak Temperature	8 minutes max.



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